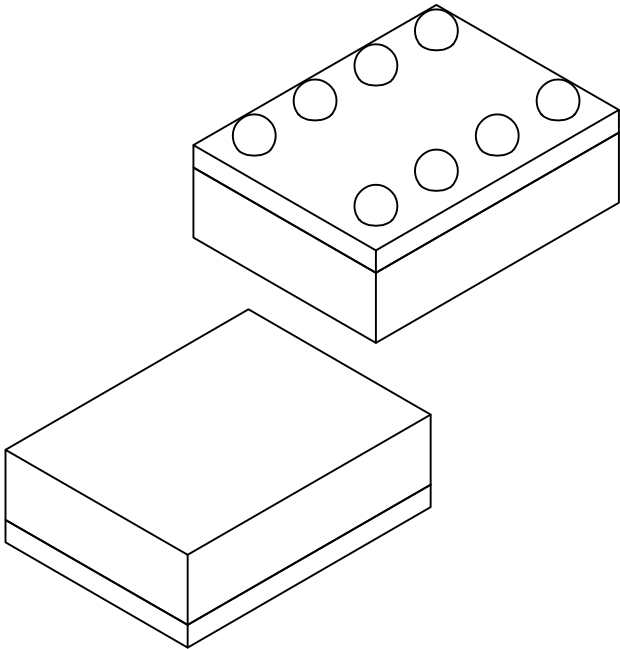


8-Ball Very Thin Fine-Pitch Ball Grid Array Package (E8B) - 1.50x2.00x0.85 mm Body [VFBGA] ; Atmel Global Package Code GXU

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	0.50		
Overall Height	A	0.73	0.79	0.85
Ball Height	A1	0.09	0.14	0.19
Mold Thickness	A2	0.40	0.45	0.50
Overall Length	D	2.00 BSC		
Ball Array Length	D1	1.50 BSC		
Overall Width	E	1.50 BSC		
Ball Array Width	E1	1.00 BSC		
Ball Diameter	b	0.20	0.25	0.30

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.